

TK PASTE CR-3520

◆ Product benefits

- A thermosetting, one-component epoxy conductive adhesive.
- Ideal for die attach applications for semiconductors, which require conductivity and heat dissipation due to its low thermal change.
- High density of silver particles provides good thermal conductivity (20 W/m·K).
- Silver particles have little variation in particle size and have good dispensing property without clogging even in fine nozzles.
- Long usable time (pot life) provides good workability.

◆ Typical properties

| | Typical value | Remarks |
|---|---------------------|--|
| Base resin | One-component epoxy | Contains solvent |
| Silver content (wt.%) | 80-90 | Spherical silver powder |
| Appearance | Gray paste | |
| Viscosity (Pa·s) | 15-25 | E type viscosity meter: 5rpm at 25°C |
| Specific gravity (-) | 4.6 | At 25°C |
| How to use | Air puls dispenser | Internal diameter of needle: >0.1mm |
| Storage condition | -10°C or below | Shelf life: 6months after manufacture |
| Pot life (hr) | 24 | At 25°C |
| Typical curing schedule | 180°C×1hr | Preheating 130°Cx 0.5hr step cure is recommended to avoid voids. |
| Specific resistance (Ω·cm) | 5×10 ⁻⁵ | 4-terminal method |
| Glass transition temperature (T _g) (°C) | 47 | DMA method |
| Storage modulus (GPa) | 7.4 | DMA method at 25°C |
| Coefficient of thermal expansion (ppm/°C) | 45 | α1 |
| | 100 | α2 |

Data in this document is based on evaluation results and does NOT guarantee product characteristics at use.
Make sure to try the product with equipment and adherend to be used.